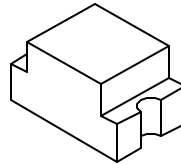
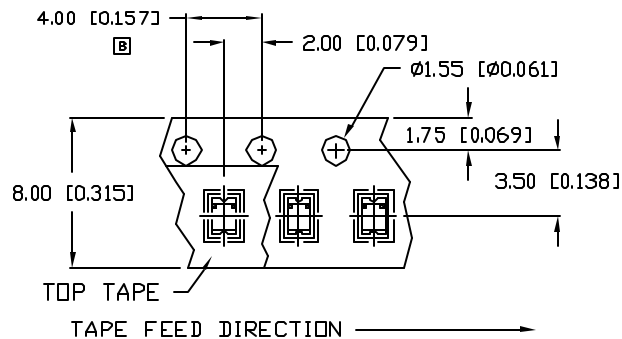
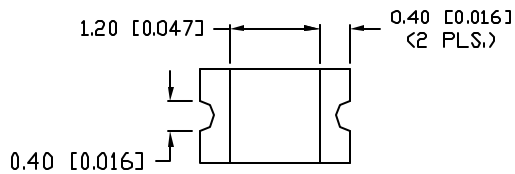
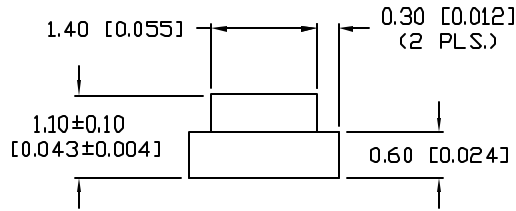
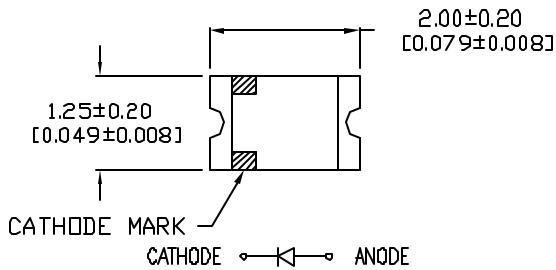
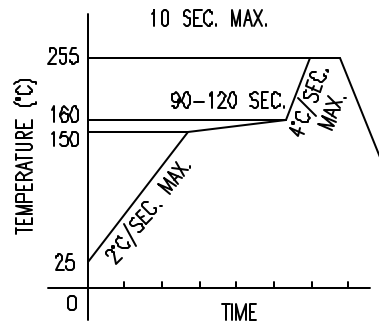


UNCONTROLLED DOCUMENT

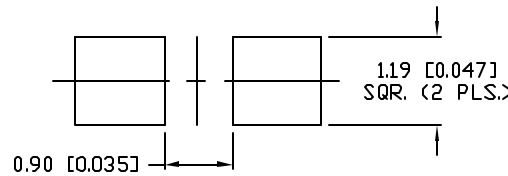


LEAD FREE REFLOW PROFILE



TOTAL TIME ABOVE 220°C IS 60 SECONDS MAX.

RECOMMENDED SOLDER PAD LAYOUT



PART NUMBER
SML-LX0805SRC-TR

REV.
G

REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	E.C.N. #10514.	5.7.99
B	E.C.N. #10644. & REDRAWN IN 3D.	7.18.00
C	E.C.N. #10751.	5.31.01
D	E.C.N. #10784.	9.8.01
E	E.C.N. #10862.	5.9.02
F	E.C.N. #10967.	3.14.03
G	E.C.N. #11148.	1.17.05

ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ $I_f=20\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		660		nm	
FORWARD VOLTAGE		1.7	2.2	V _f	
REVERSE VOLTAGE	5.0			V _r	I _f =100μA
AXIAL INTENSITY		25		mcad	I _f =20mA
VIEWING ANGLE		140		2x theta	
EMITTED COLOR:	RED				
EPOXY LENS FINISH:	WATER CLEAR				

LIMITS OF SAFE OPERATION AT 25°C

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	160	mA
STEADY CURRENT	25	mA
POWER DISSIPATION	100	mW
DERATE FROM 25°C	-1.2	mW/°C
OPERATING TEMP.	-40 TO +85	°C
STORAGE TEMP.	-40 TO +85	°C

* t<10μS

NOTES:

1. THE CATHODE IS ORIENTED TOWARDS THE TAPE SPROCKET HOLE.



CAUTION: MOISTURE SENSITIVE DEVICE
PER JEDEC LEVEL 4 STANDARDS

*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (+0.039), X.X=±0.5 (+0.020), X.XX=±0.25 (+0.010), X.XXX=±0.127 (+0.005), LEAD SIZE=±0.05 (0.002), LEAD LENGTH=±0.75 (+0.030), MIN.= +DECIMAL PRECISION -0.00, MAX.= +0.00 -DECIMAL PRECISION

REV. G PART NUMBER SML-LX0805SRC-TR

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TW WEB: www.lumex.com.tw

2.0mm x 1.25mm PCB SURFACE MOUNT,
660nm SUPER RED, WATER CLEAR LENS, TAPE AND REEL.

RELIABILITY NOTE
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY: CT CHECKED BY: APPROVED BY: DATE: 1.29.99
PAGE: 1 OF 1
SCALE: N/A